- **2-V to 5.5-V V_{CC} Operation**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Outputs Are Disabled During Power Up and Power Down With Inputs Tied to V_{CC}**
- **Support Mixed-Mode Voltage Operation on All Ports**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

description/ordering information

These hex buffers/drivers are designed for 2-V to 5.5-V V_{CC} operation.

The 'LV07A devices perform the Boolean function Y = A in positive logic.

The open-drain outputs require pullup resistors to perform correctly and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

SN54LV07A . . . J OR W PACKAGE
SN74LV07A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)

1A	1	14	V_{CC}
1Y	2	13	6A
2A	3	12	6Y
2Y	4	11	5A
3A	5	10	5Y
3Y	6	9	4A
GND	7	8	4Y
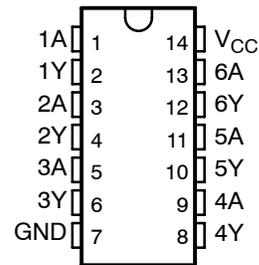
SN54LV07A . . . FK PACKAGE
(TOP VIEW)
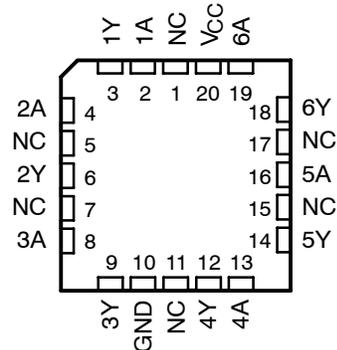
NC – No internal connection

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SOIC – D	Tube of 50	SN74LV07AD	LV07A
		Reel of 2500	SN74LV07ADR	
	SOP – NS	Reel of 2000	SN74LV07ANSR	74LV07A
	SSOP – DB	Reel of 2000	SN74LV07ADBR	LV07A
	TSSOP – PW	Tube of 90	SN74LV07APW	LV07A
		Reel of 2000	SN74LV07APWRG3	
		Reel of 250	SN74LV07APWT	
	TVSOP – DGV	Reel of 2000	SN74LV07ADGVR	LV07A
−55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV07AJ	SNJ54LV07AJ
	CFP – W	Tube of 150	SNJ54LV07AW	SNJ54LV07AW
	LCCC – FK	Tube of 55	SNJ54LV07AFK	SNJ54LV07AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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TEXAS INSTRUMENTS

FUNCTION TABLE
(each buffer/driver)

INPUT A	OUTPUT Y
H	H
L	L

logic diagram, each buffer/driver (positive logic)

A ————▷◇——— Y

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . –0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O
   (see Note 1) . . . . –0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$) . . . . –20 mA
Output clamp current, I_{OK} ($V_O < 0$) . . . . –50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . –35 mA
Continuous current through V_{CC} or GND . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . 86°C/W
                                                         DB package . . . . 96°C/W
                                                         DGV package . . . . 127°C/W
                                                         NS package . . . . 76°C/W
                                                         PW package . . . . 113°C/W
Storage temperature range, T_{stg} . . . . –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
        2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

			SN54LV07A		SN74LV07A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 4.5 V to 5.5 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 2.3 V to 2.7 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 3 V to 3.6 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	5.5	0	5.5	V
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	µA
		V_{CC} = 2.3 V to 2.7 V		2		2	mA
		V_{CC} = 3 V to 3.6 V		8		8	
		V_{CC} = 4.5 V to 5.5 V		16		16	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 2.3 V to 2.7 V		200		200	ns/V
		V_{CC} = 3 V to 3.6 V		100		100	
		V_{CC} = 4.5 V to 5.5 V		20		20	
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	SN54LV07A			SN74LV07A			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{OL}	I_{OL} = 50 µA		2 V to 5.5 V			0.1			0.1	V
	I_{OL} = 2 mA		2.3 V			0.4			0.4	
	I_{OL} = 8 mA		3 V			0.44			0.44	
	I_{OL} = 16 mA		4.5 V			0.55			0.55	
I_I	V_I = 5.5 V or GND		0 to 5.5 V			±1			±1	µA
I_{OH}	V_I = V_{IH},	V_{OH} = V_{CC}	5.5 V			±2.5			±2.5	µA
I_{CC}	V_I = V_{CC} or GND,	I_O = 0	5.5 V			20			20	µA
I_{off}	V_I or V_O = 0 to 5.5 V		0			5			5	µA
C_i	V_I = V_{CC} or GND		3.3 V		1.6			1.6		pF

TEXAS INSTRUMENTS

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3

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV07A		SN74LV07A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 15 pF		6.6*	10.4*	1*	13*	1	13	ns
t_{PHL}	A	Y			7.5*	10.4*	1*	13*	1	13	
t_{PLH}	A	Y	C_L = 50 pF		11.1	15.2	1	18	1	18	ns
t_{PHL}	A	Y			9.6	15.2	1	18	1	18	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV07A		SN74LV07A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 15 pF		5*	7.1*	1*	8.5*	1	8.5	ns
t_{PHL}	A	Y			5*	7.1*	1*	8.5*	1	8.5	
t_{PLH}	A	Y	C_L = 50 pF		8.2	10.6	1	12	1	12	ns
t_{PHL}	A	Y			6.6	10.6	1	12	1	12	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV07A		SN74LV07A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 15 pF		3.8*	5.5*	1*	6.5*	1	6.5	ns
t_{PHL}	A	Y			3.4*	5.5*	1*	6.5*	1	6.5	
t_{PLH}	A	Y	C_L = 50 pF		5.7	7.5	1	8.5	1	8.5	ns
t_{PHL}	A	Y			4.5	7.5	1	8.5	1	8.5	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER		SN74LV07A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.4	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.1	–0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 10 MHz	3.3 V	2.9	pF
			5 V	5.3	

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INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION
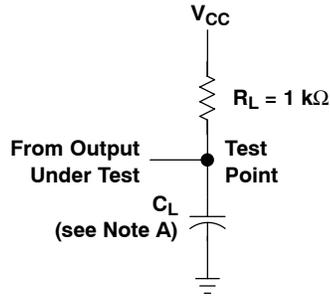
**LOAD CIRCUIT FOR
OPEN-DRAIN OUTPUTS**
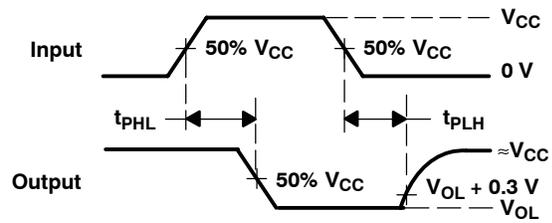
**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES**

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
C. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LV07AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADGVRG4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV07A	Samples
SN74LV07ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV07A	Samples
SN74LV07APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LV07APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples
SN74LV07APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV07A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV07ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV07ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV07ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV07ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV07APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV07APWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV07APWRG3	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV07APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV07APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS
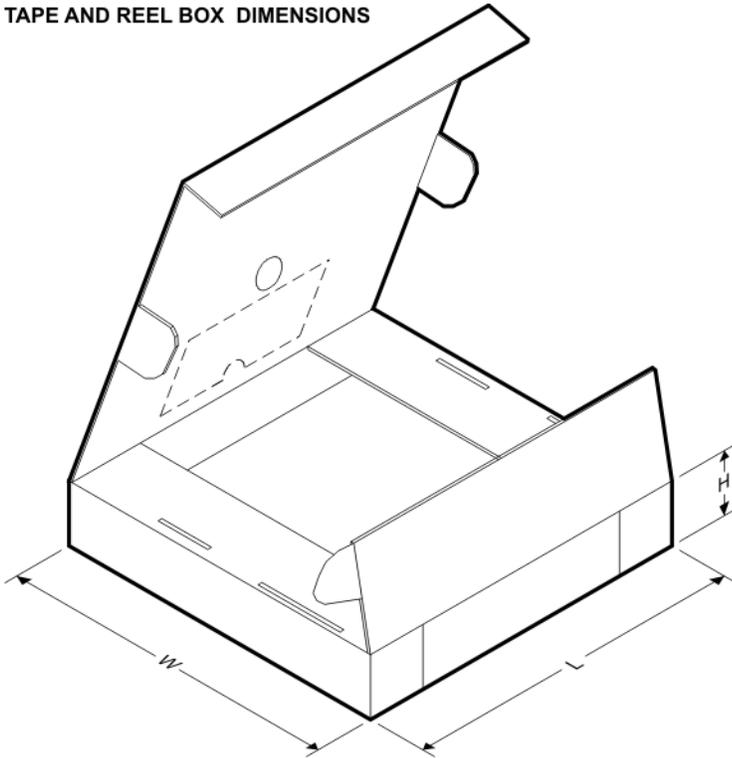
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV07ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LV07ADGVR	TVSOP	DGV	14	2000	367.0	367.0	35.0
SN74LV07ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LV07ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74LV07APWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LV07APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
SN74LV07APWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
SN74LV07APWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LV07APWT	TSSOP	PW	14	250	367.0	367.0	35.0

MECHANICAL DATA

MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

DGV (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN
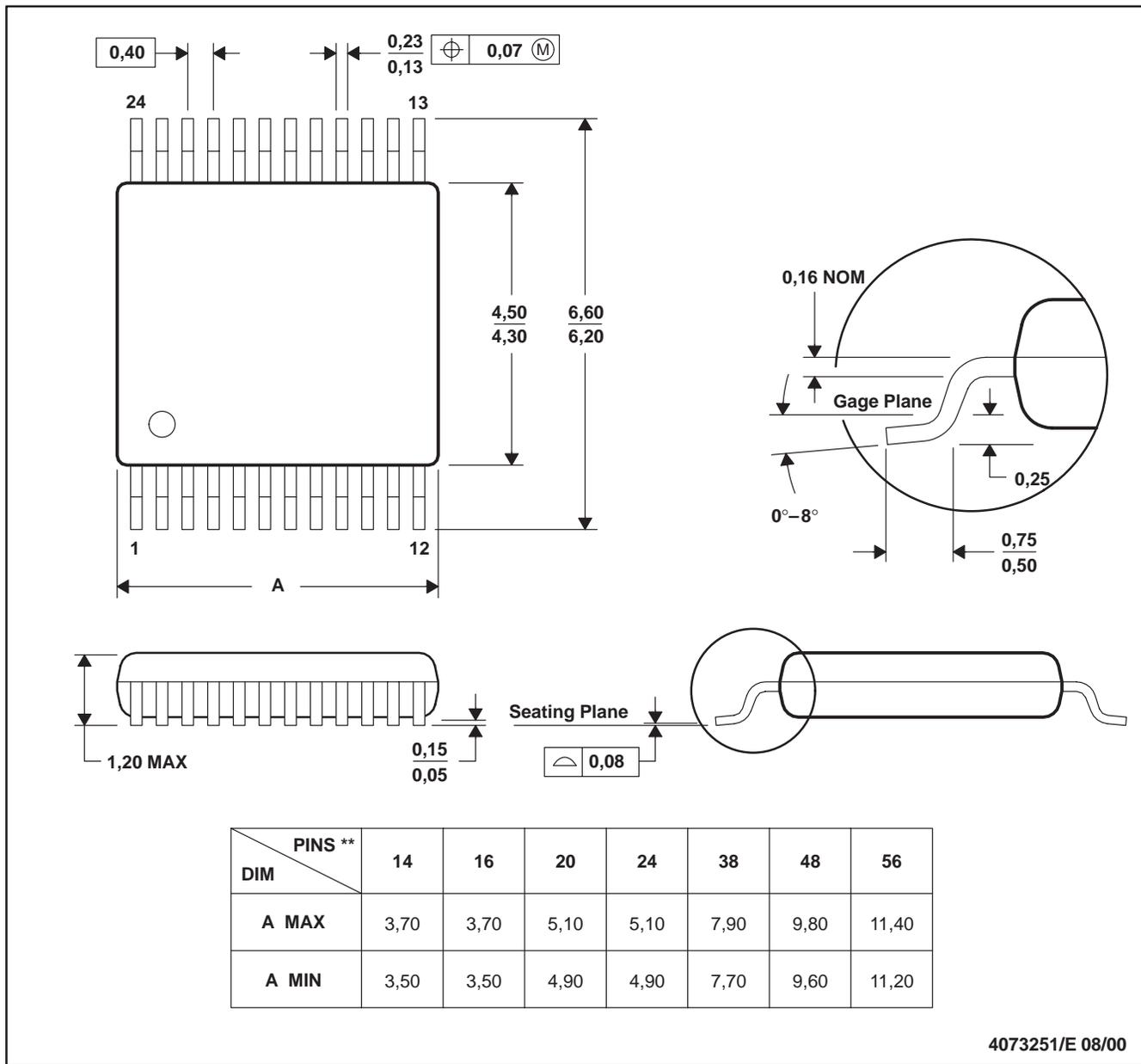
0,40

$\frac{0,23}{0,13}$ ⊕ 0,07 Ⓜ

24   13

$\frac{4,50}{4,30}$ $\frac{6,60}{6,20}$

0,16 NOM

Gage Plane

0,25

0°–8°

$\frac{0,75}{0,50}$

1   12

A

1,20 MAX

$\frac{0,15}{0,05}$

Seating Plane

⌒ 0,08

DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)   D

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) M

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11
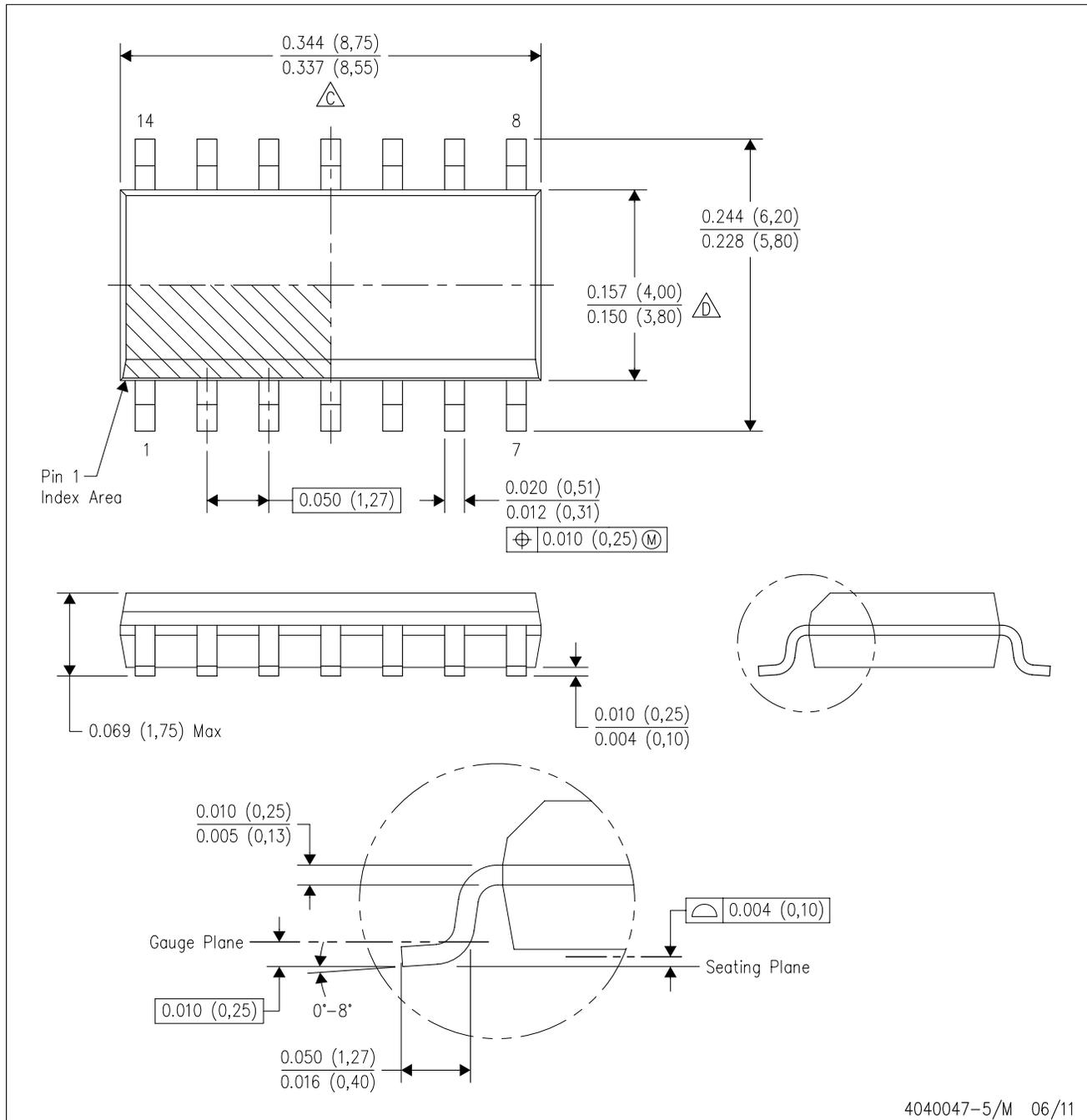
NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
          C.   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
               not exceed 0.006 (0,15) each side.
          D.   Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
   E.   Reference JEDEC MS−012 variation AB.
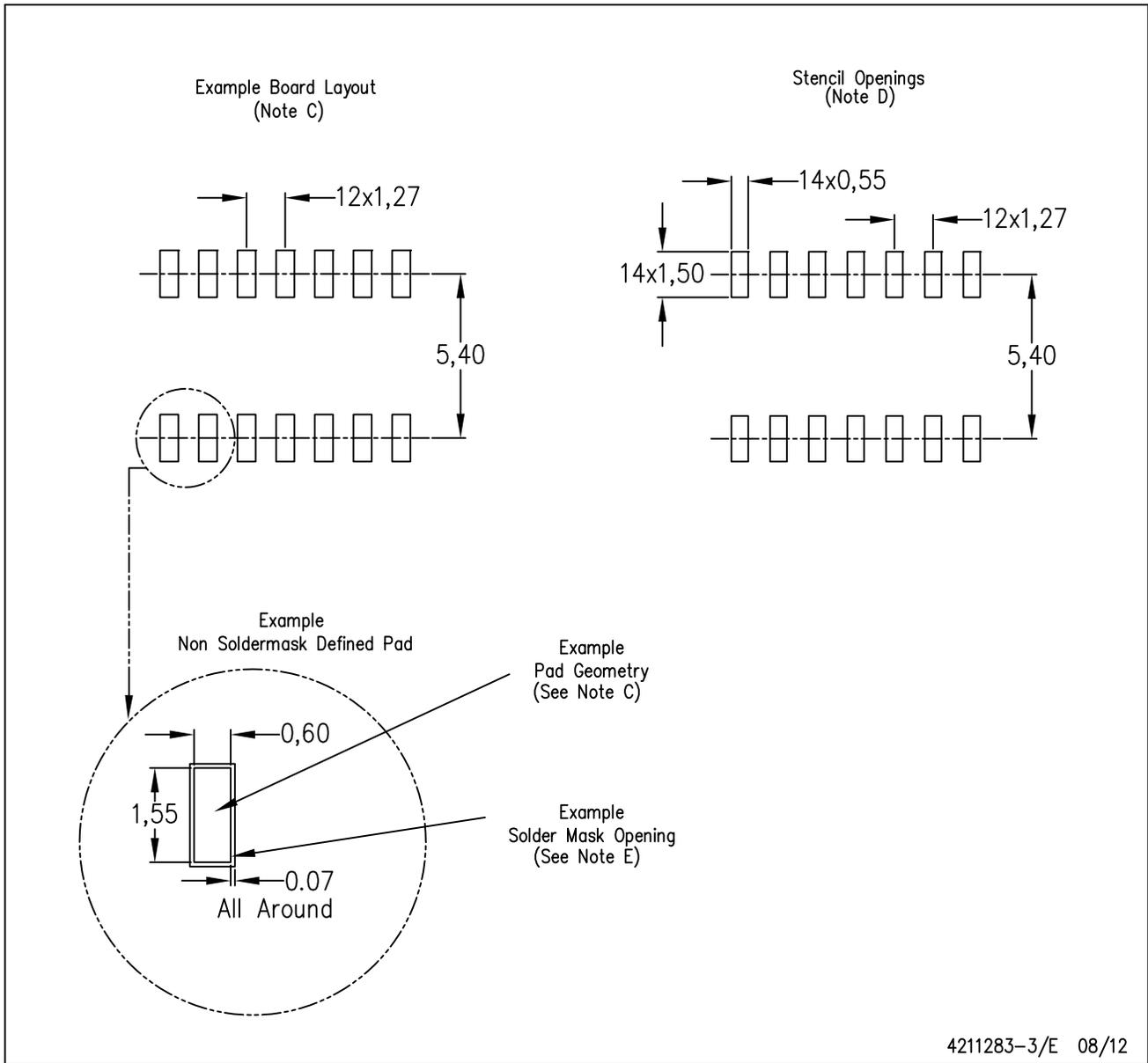
TEXAS INSTRUMENTS
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D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

Example
Solder Mask Opening
(See Note E)

1,55

0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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PW (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0,65

0,30
0,19

⊕ 0,10 Ⓜ

14   8

△D 4,50
     4,30

6,60
6,20

1   7

5,10
4,90

△C

0,15 NOM

Gage Plane

0°−8°

0,25

0,75
0,50

1,20 MAX

0,15
0,05

Seating Plane

⌓ 0,10

4040064−3/G 02/11
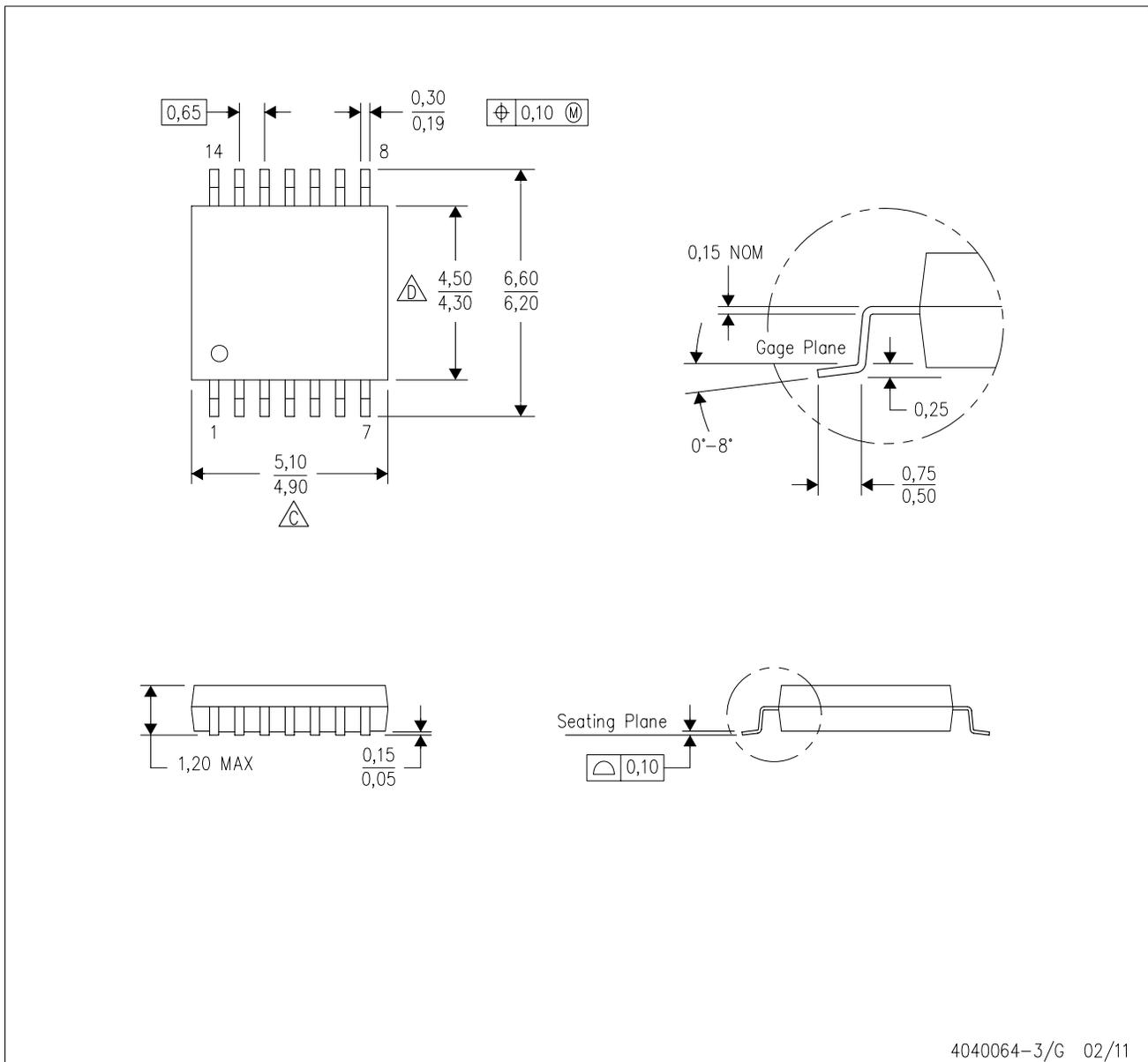
NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
        △C   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0,15 each side.
        △D   Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
         E.   Falls within JEDEC MO−153

PW (R–PDSO–G14)   PLASTIC SMALL OUTLINE
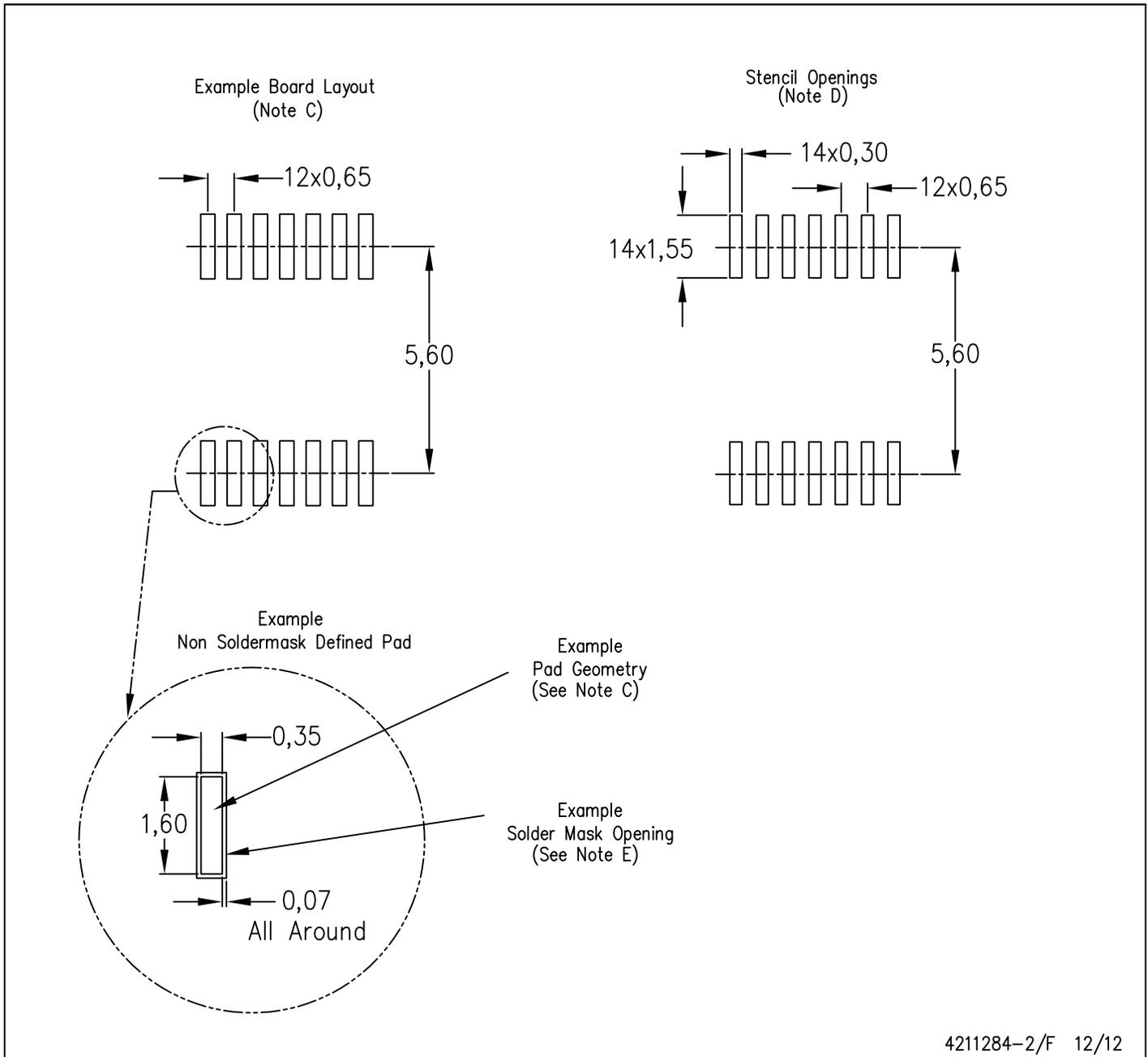
Example Board Layout
(Note C)

←12x0,65

5,60

Stencil Openings
(Note D)

14x0,30

←12x0,65

14x1,55

5,60

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,35

1,60

Example
Solder Mask Opening
(See Note E)

0,07
All Around

4211284–2/F   12/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC–7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN
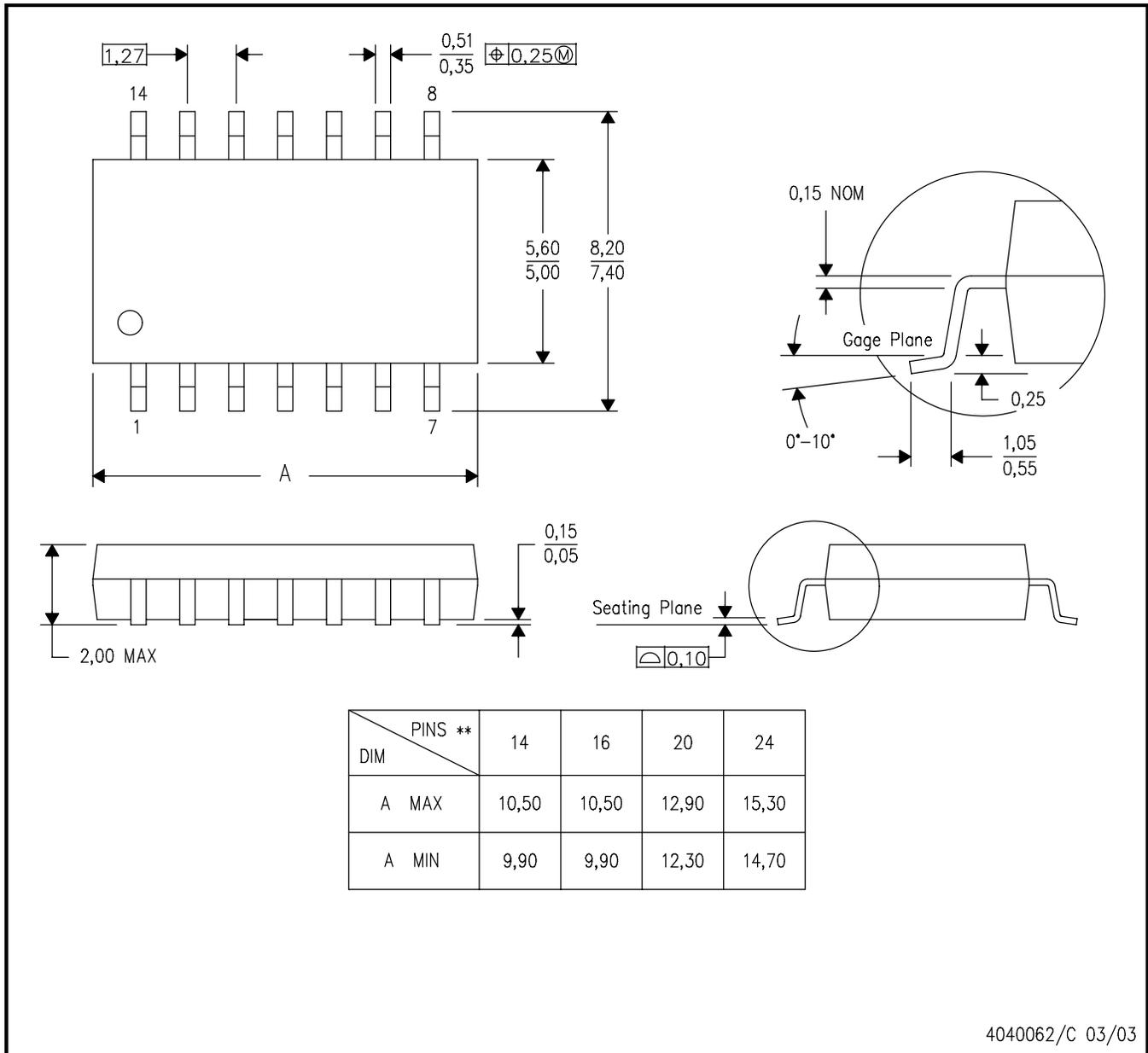
1,27

0,51 / 0,35   ⊕ 0,25Ⓜ

14   8

5,60 / 5,00   8,20 / 7,40

1   7

A

0,15 NOM

Gage Plane

0,25

0°–10°   1,05 / 0,55

0,15 / 0,05

2,00 MAX

Seating Plane

▱ 0,10

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**) PLASTIC SMALL-OUTLINE

28 PINS SHOWN
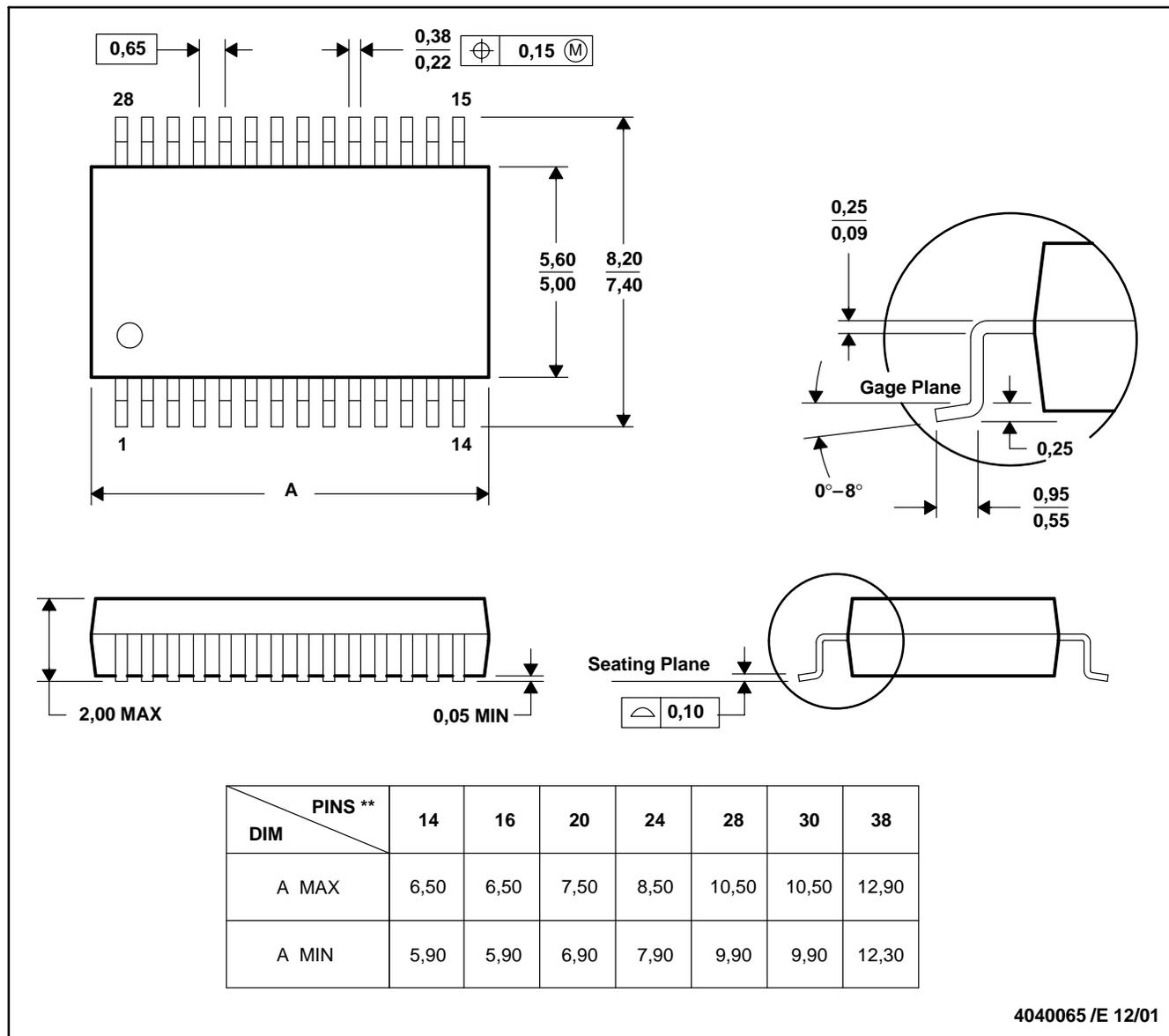
0,65

$\frac{0,38}{0,22}$ ⊕ 0,15 (M)

28   15

$\frac{5,60}{5,00}$ $\frac{8,20}{7,40}$

$\frac{0,25}{0,09}$

Gage Plane

0,25

0°–8° $\frac{0,95}{0,55}$

1   14

A

2,00 MAX   0,05 MIN

Seating Plane

△ 0,10

PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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